REMARKS

Figure numbers have been corrected in the specification above.

Changes to the claims merely clarify the claims and should not require further consideration or search. For example, claim 33 claimed "A process of manufacturing an electronic device cover", so changing the claim language to "forming [[a]] an electronic device cover member" in claim 33 should not require further consideration or search.

Claims 1-8, 12, 17-20 and 33 were rejected under 35 U.S.C. §102(b) as being anticipated by Nishihara et al. (US 5,118,458). Claims 9-10, 13 and 14 were rejected under 35 U.S.C. §103(a) as being unpatentable over Nishihara et al. (US 5,118,458) in view of Official Notice. Claims 11 and 15 were rejected under 35 U.S.C. §103(a) as being unpatentable over Nishihara et al. (US 5,118,458) in view of Official Notice and Politycki et al. (US 3,767,538). Claim 16 was rejected under 35 U.S.C. §103(a) as being unpatentable over Nishihara et al. (US 5,118,458) in view of Official Notice, Politycki et al. (US 3,767,538) and Murakami et al. (US 4,239,813). The examiner is requested to reconsider these rejections.

Claim 1 has been amended to clarify applicants' invention. Claim 1 claims that the process comprises forming an electronic device cover member for an electronic device. The examiner stated that a method of moulding a cover for an electronic device is not recited in the rejected claims. This was incorrect. Old claim 1 claimed forming a cover member for an electronic device, and claim 2 claimed arranging the

electrical circuitry element in a mould and moulding the cover member onto the electrical circuitry element.

As noted previously, Nishihara does not relate to a method of forming a cover for an electronic device. As noted in the application, examples of a electronic device are a mobile telephone, a camera, or an input device. Nishihara only discloses manufacturing an article, such as a printed circuit board, having components within it. Nishihara does not disclose or suggest forming an electronic device cover member. Nishihara discloses a method of stacking layers of flexible circuits together and molding plastic onto the stacked layers. There is no disclosure or suggestion of the molding process in Nishihara forming an electronic device cover member as recited in claim 1. There is no disclosure or suggestion in Nishihara of the resin 27 of the product 28 forming an electronic device cover member.

Claim 1 also claims providing an integral connector structure on the cover member for connecting the electrical circuitry to an electronic component. There is no disclosure or suggestion in Nishihara of providing an integral connector structure on the resin 27 of the product 28 for connecting the electrical circuitry to an electronic component.

The features of claim 1 are not "anticipated" by Nishihara. Therefore, claim 1 is patentable and should be allowed.

Though dependent claims 2-20 contain their own allowable subject matter, these claims should at least be allowable due to their dependence from allowable claim 1. However, to

expedite prosecution at this time, no further comment will be made.

Applicants' attorney also hereby challenges the examiner's "Official Notice" mentioned in the office action. In accordance with MPEP §2144.03 the examiner is requested to cite a reference in support of his positions.

Claim 33 has been amended above to clarify applicants' claimed invention. Claim 33 claims forming an electronic device cover member. As noted above with respect to claim 1, Nishihara does not relate to a method of forming a cover for an electronic device. Nishihara only discloses manufacturing an article such as a printed circuit board having components within it. Nishihara does not disclose or suggest forming an electronic device cover member. Nishihara discloses a method of stacking layers of flexible circuits together and molding plastic onto the stacked layers. However, there is no disclosure or suggestion of the molding process in Nishihara forming an electronic device cover member as recited in claim 33. There is no disclosure or suggestion in Nishihara of the resin 27 of the product 28 forming an electronic device cover member.

Claim 33 also claims providing on the cover member a connector structure for connecting the electrical circuitry to an electronic component, wherein the connector structure is integrally formed with the cover member during the incorporating of the electrical circuitry into the cover member during the forming of the cover member.. There is no disclosure or suggestion in Nishihara of providing an integral

connector structure on the resin 27 of the product 28 for connecting the electrical circuitry to an electronic component.

The features of claim 33 are not "anticipated" by Nishihara. Therefore, claim 33 is patentable and should be allowed.

For all of the foregoing reasons, it is respectfully submitted that all of the claims now present in the application are clearly novel and patentable over the prior art of record. Accordingly, favorable reconsideration and allowance is respectfully requested. Should any unresolved issue remain, the examiner is invited to call applicants' attorney at the telephone number indicated below.

Respectfully submitted,

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